

### High and Low Side Driver

#### **Features**

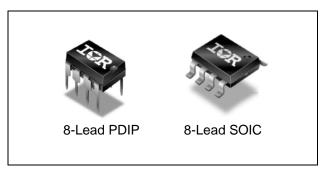
- Floating channel designed for bootstrap operation
- Fully operational to 200V
- Tolerant to negative transient voltage, dV/dt immune
- Gate drive supply range from 10 to 20V
- Independent low and high side channels
- Input logic HIN/LIN active high
- Undervoltage lockout for both channels
- 3.3V and 5V logic compatible
- CMOS Schmitt-triggered inputs with pull-down
- Matched propagation delay for both channels

# **Product Summary**

V <sub>OFFSET</sub> (max)	200V
I <sub>O+/-</sub> (typ)	1.0A / 1.0A
$V_{OUT}$	10 – 20V
t <sub>on/off</sub> (typ)	80ns & 60ns
Delay Matching (max)	20ns

#### **Description**

The IR2011 is a high power, high speed power MOSFET driver with independent high and low side referenced output Package Options channels. Logic inputs are compatible with standard CMOS or LSTTL output, down to 3.0V logic. The output drivers feature a high pulse current buffer stage designed for minimum driver cross-conduction. Propagation delays are matched to simplify use in high frequency applications. The floating channel can be used to drive an N-channel power MOSFET in the high side configuration which operates up to 200 volts. Proprietary HVIC and latch immune CMOS technologies enable ruggedized monolithic construction.



### **Applications**

- Converters
- DC motor drive

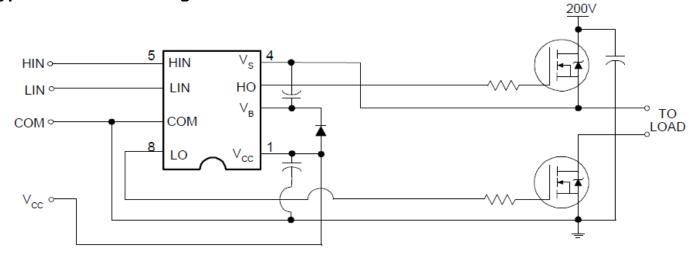
### **Ordering Information**

Dana Bart Namel an		Standar	d Pack	On lawylla Davi Namelan
Base Part Number	Package Type	Form	Quantity	Orderable Part Number
IR2011PBF	PDIP8	Tube	50	IR2011PBF
IR2011SPBF	SO8N	Tube	95	IR2011SPBF
IR2011SPBF	SO8N	Tape and Reel	2500	IR2011STRPBF



### **Typical Connection Diagram**

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(Refer to Lead Assignments for correct configuration.) This diagram shows electrical connections only. Please refer to our Application Notes and Design Tips for proper circuit board layout



#### **Absolute Maximum Ratings**

Absolute maximum ratings indicate sustained limits beyond which damage to the device may occur. All voltage parameters are absolute voltages referenced to COM. The thermal resistance and power dissipation ratings are measured under board mounted and still air conditions.

Symbol	Definition	Min.	Max.	Units			
$V_{B}$	High side floating supply voltage		-0.3	225			
$V_S$	High side floating supply offset volta	ige	V <sub>B</sub> - 25	$V_B + 0.3$			
$V_{HO}$	High side floating output voltage		V <sub>S</sub> - 0.3	V <sub>B</sub> + 0.3	V		
V <sub>cc</sub>	Low side fixed supply voltage		-0.3	25	]		
$V_{LO}$	Low side output voltage		-0.3	V <sub>CC</sub> + 0.3			
V <sub>IN</sub>	Logic input voltage (HIN, LIN)		-0.3	V <sub>CC</sub> + 0.3			
dV <sub>s</sub> /dt	Allowable offset supply voltage trans	sient	_	50	V/ns		
Б	Package power dissipation	8-Lead PDIP	_	1.0	10/		
$P_D$	<sup>D</sup> @ T <sub>A</sub> ≤ +25°C 8-Lead SO	8-Lead SOIC	_	0.625	W		
Dul	Thermal resistance, junction to	8-Lead PDIP	_	125	0000		
Rtn <sub>JA</sub>	Rth <sub>JA</sub> ambient		ambient 8-Lead SOIC	8-Lead SOIC	_	200	°C/W
TJ	Junction temperature	_	150				
T <sub>S</sub>	Storage temperature	-55	150	°C			
TL	Lead temperature (soldering, 10 sec	conds)	_	300			

### **Recommended Operating Conditions**

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For proper operation the device should be used within the recommended conditions. The  $V_S$  and COM offset ratings are tested with all supplies biased at 15V differential.

Symbol	Definition	Min.	Max.	Units
$V_B$	High side floating supply absolute voltage	V <sub>S</sub> + 10	V <sub>S</sub> + 20	
$V_S$	High side floating supply offset voltage	†	200	
$V_{HO}$	High side floating output voltage	Vs	V <sub>B</sub>	V
$V_{CC}$	Low side fixed supply voltage	10	20	]
$V_{LO}$	Low side output voltage	0	V <sub>CC</sub>	
$V_{IN}$	Logic input voltage (HIN, LIN)	COM	5.5	
T <sub>A</sub>	Ambient temperature	-40	125	°C

 $<sup>^{+}</sup>$  Logic operational for  $V_S$  of -4 to +200V. Logic state held for  $V_S$  of -4V to -V<sub>BS</sub>.



### **Dynamic Electrical Characteristics**

 $V_{BIAS}$  ( $V_{CC}$ ,  $V_{BS}$ ) = 15V,  $C_L$  = 1000pF and  $T_A$  = 25°C unless otherwise specified. Figure 1 shows the timing definitions.

Symbol	Definition	Min.	Тур.	Max.	Units	Test Conditions
t <sub>on</sub>	Turn-on propagation delay		80	_		V <sub>S</sub> = 0V
t <sub>off</sub>	Turn-off propagation delay	_	75	_		V <sub>S</sub> = 200V
t <sub>r</sub>	Turn-on rise time		35	50		
t <sub>f</sub>	Turn-off fall time	_	20	35	ns	
DM1	Turn-on delay matching   t <sub>on</sub> (H) - t <sub>on</sub> (L)	_	_	20		
DM2	Turn-off delay matching   t <sub>off</sub> (H) - t <sub>off</sub> (L)	_	_	20		

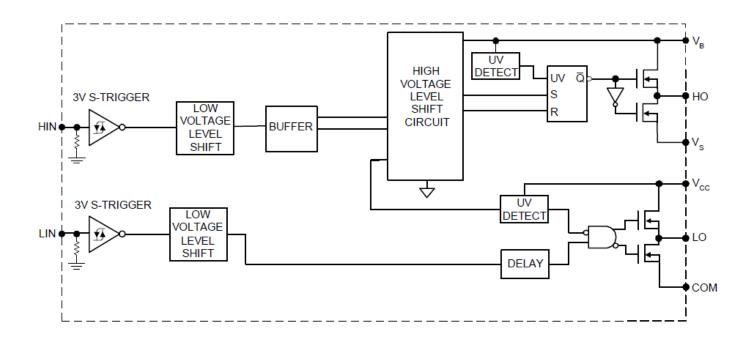
#### **Static Electrical Characteristics**

 $V_{BIAS}$  ( $V_{CC}$ ,  $V_{BS}$ ) = 15V and  $T_A$  = 25°C unless otherwise specified. The  $V_{IN}$ ,  $V_{TH}$  and  $I_{IN}$  parameters are referenced to COM and are applicable to all logic input leads: HIN and LIN. The  $V_O$  and  $I_O$  parameters are referenced to COM and are applicable to the respective output leads: HO or LO.

Symbol	Definition	Min.	Тур.	Max.	Units	Test Conditions
V <sub>IH</sub>	Logic "1" input voltage	2.2	_			$V_{CC} = 10V - 20V$
$V_{IL}$	Logic "0" input voltage		_	0.7	V	V <sub>CC</sub> = 10V - 20V
$V_{OH}$	High level output voltage, V <sub>BIAS</sub> - V <sub>O</sub>		_	2.0	_ v	$I_{O} = 0A$
$V_{OL}$	Low level output voltage, V <sub>O</sub>			0.2		$I_O = 20mA$
$I_{LK}$	Offset supply leakage current			50		$V_{B} = V_{S} = 200V$
$I_{QBS}$	Quiescent V <sub>BS</sub> supply current		90	210		$V_{IN} = 0V \text{ or } 3.3V$
I <sub>QCC</sub>	Quiescent V <sub>CC</sub> supply current		140	230	μA	V <sub>IN</sub> = 0 V 0I 3.3 V
I <sub>IN+</sub>	Logic "1" input bias current		7.0	20		$V_{IN} = 3.3V$
I <sub>IN-</sub>	Logic "0" input bias current		_	1.0		$V_{IN} = 0V$
V <sub>BSUV+</sub>	V <sub>BS</sub> supply undervoltage positive going threshold	8.2	9.0	9.8		
V <sub>BSUV</sub> -	V <sub>BS</sub> supply undervoltage negative going threshold	7.4	8.2	9.0	\ \ <u>\</u>	
V <sub>CCUV+</sub>	V <sub>CC</sub> supply undervoltage positive going threshold	8.2	9.0	9.8	V	
V <sub>CCUV-</sub>	V <sub>CC</sub> supply undervoltage negative going threshold	7.4	8.2	9.0		
I <sub>O+</sub>	Output high short circuit pulsed current	_	1.0	_	^	V <sub>O</sub> = 0V, PW ≤ 10 μs
I <sub>O-</sub>	Output low short circuit pulsed current	_	1.0	_	A	V <sub>O</sub> = 15V PW ≤ 10 μs



### **Functional Block Diagram**

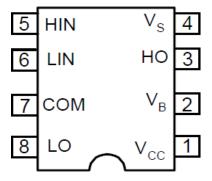


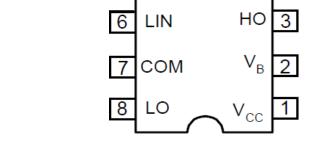


### **Lead Definitions**

Symbol	Description	
HIN	Logic input for high side gate driver outputs (HO), in phase	
LIN	Logic input for low side gate driver outputs (LO), in phase	
$V_B$	High side floating supply	
НО	High side gate drive output	
Vs	High side floating supply return	
V <sub>CC</sub>	Low side supply	
LO	Low side gate drive output	
COM	Low side return	

### **Lead Assignments**





HIN

8-Lead PDIP

8-Lead SOIC



### **Application Information and Additional Details**

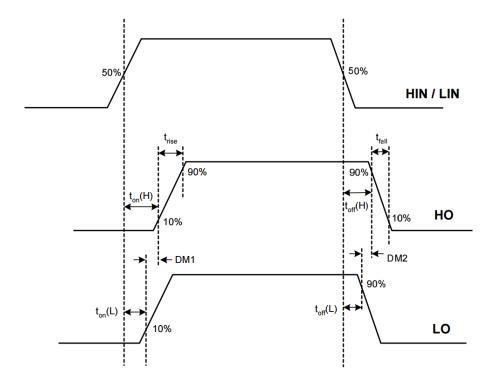
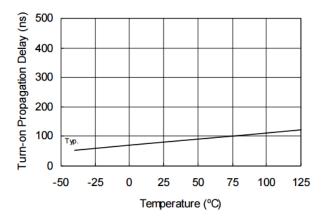


Figure 1. Timing Diagram





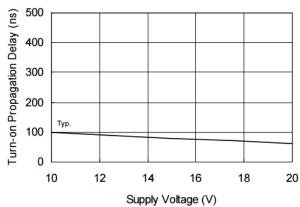
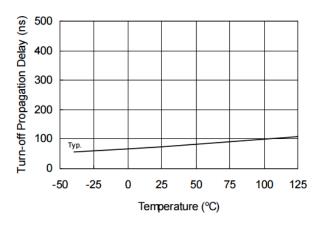


Figure 2A. Turn-on Propagation Delay vs. Temperature

Figure 2B. Turn-on Propagation Delay vs. Supply Voltage



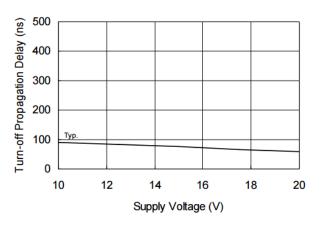
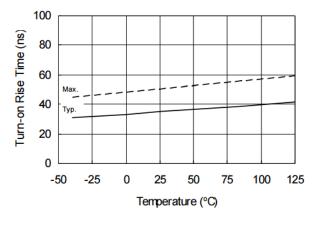


Figure 3A. Turn-off Propagation Delay vs. Temperature

Figure 3B. Turn-off Propagation Delay vs. Supply Voltage



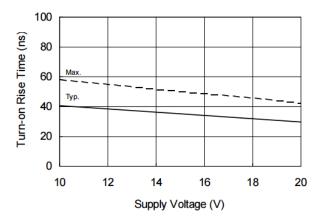
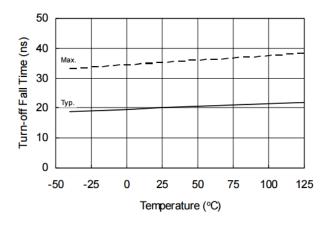


Figure 4A. Turn-on Rise Time vs. Temperature

Figure 4B. Turn-on Rise Time vs. Supply Voltage





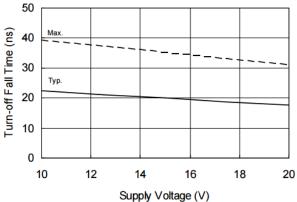
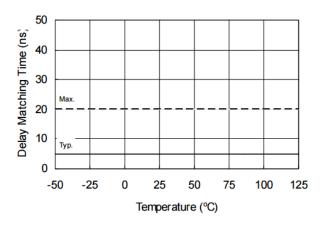


Figure 5A. Turn-off Fall Time vs. Temperature

Figure 5B. Turn-off Fall Time vs. Supply Voltage



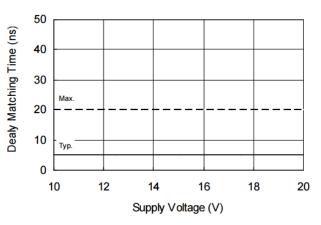
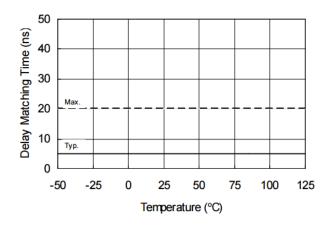


Figure 6A. Turn-on Delay Matching vs. Temperature

Figure 6B. Turn-on Delay Matching Time vs. Supply Voltage



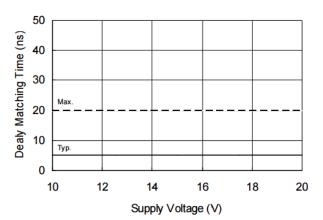
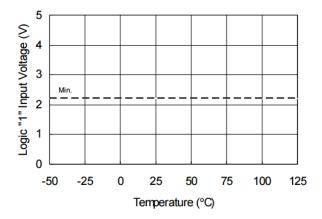


Figure 7A. Turn-off Delay Matching Time vs. Temperature

Figure 7B. Turn-off Delay Matching Time vs. Supply Voltage





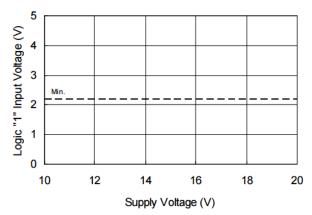
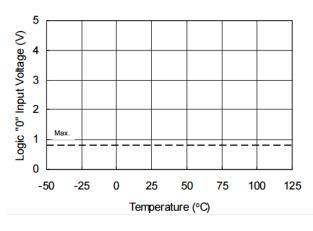


Figure 8A. Logic "1" Input Voltage vs. Temperature

Figure 8B. Logic "1" Input Voltage vs. Supply Voltage



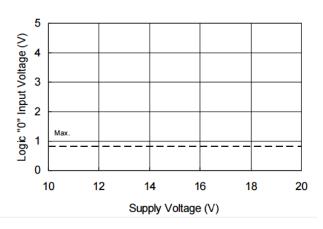
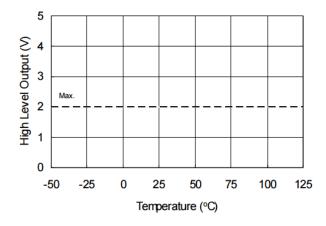


Figure 9A. Logic "0" Input Voltage vs. Temperature

Figure 9B. Logic "0" Input Voltage vs. Supply Voltage



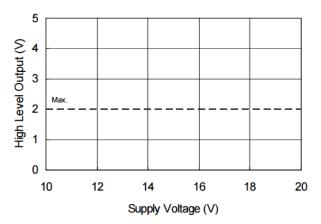
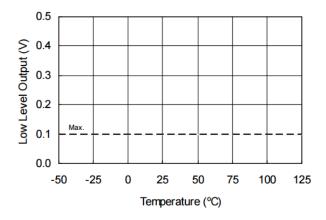


Figure 10A. High Level Output vs. Temperature

Figure 10B. High Level Output vs. Supply Voltage





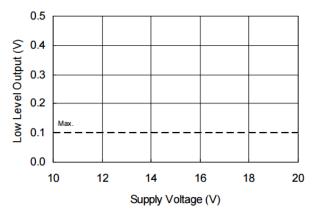


Figure 11A. Low Level Output vs. Temperature

Offset Supply Leakage Current (uA) 500 400 300 200 100 125 -50 -25 25 75 100 Temperature (°C)

Figure 11B. Low Level Output vs. Supply Voltage

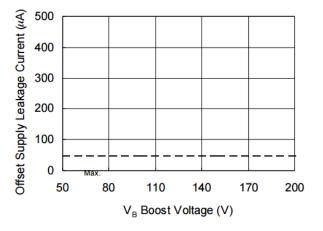


Figure 12A. Offset Supply Leakage Current vs. **Temperature** 

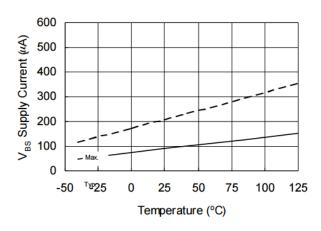


Figure 12B. Offset Supply Leakage Current vs. **Supply Voltage** 

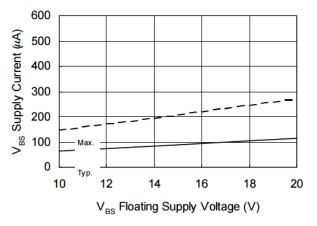
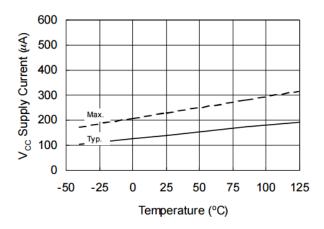


Figure 13A. V<sub>BS</sub> Supply Current vs. Temperature

Figure 13B. V<sub>BS</sub> Supply Current vs. Supply Voltage

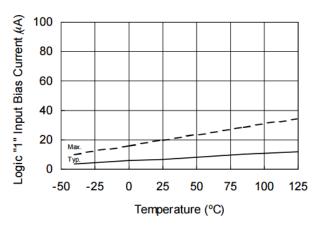




600 V<sub>cc</sub> Supply Current ("A) **500** 400 300 200 100 Тур 0 10 12 14 16 18 20 V<sub>CC</sub> Supply Voltage (V)

Figure 14A. V<sub>CC</sub> Supply Current vs. Temperature

Figure 14B. V<sub>CC</sub> Supply Current vs. V<sub>CC</sub> Supply Voltage



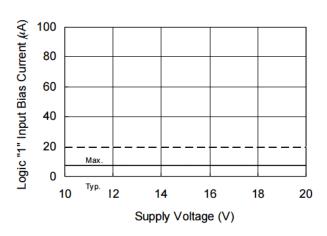
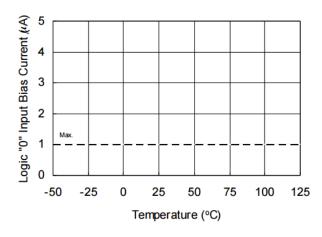


Figure 15A. Logic "1" Input Bias Current vs. Temperature

Figure 15 B. Logic "1" Input Bias Current vs. Supply Voltage



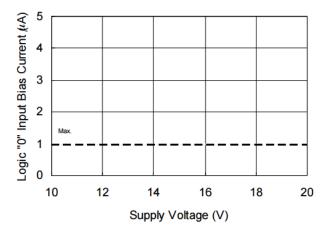


Figure 16A. Logic "0" Input Bias Current vs.
Temperature

Figure 16B. Logic "0" Input Bias Current vs. Supply Voltage



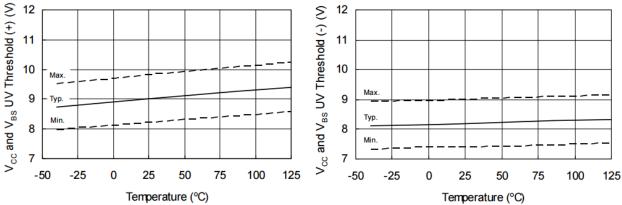
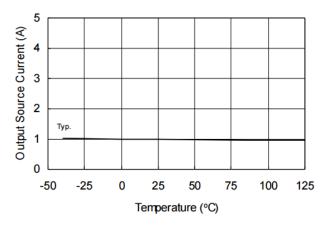


Figure 17.  $V_{CC}$  and  $V_{BS}$  Undervoltage Threshold (+) vs. Temperature

Figure 18. V<sub>CC</sub> and V<sub>BS</sub> Undervoltage Threshold (-) vs. Temperature



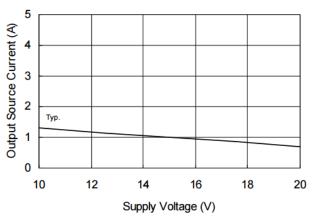
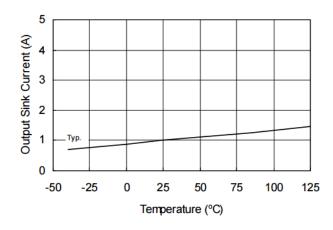


Figure 19A. Output Source Current vs. Temperature

Figure 19B. Output Source Current vs. Supply Voltage



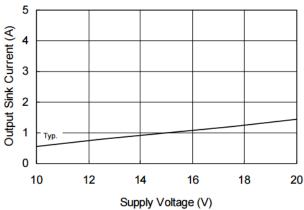


Figure 20A. Output Sink Current vs. Temperature

Figure 20B. Output Sink Currnt vs. Supply Voltage



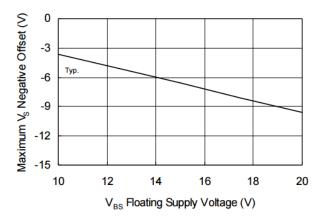
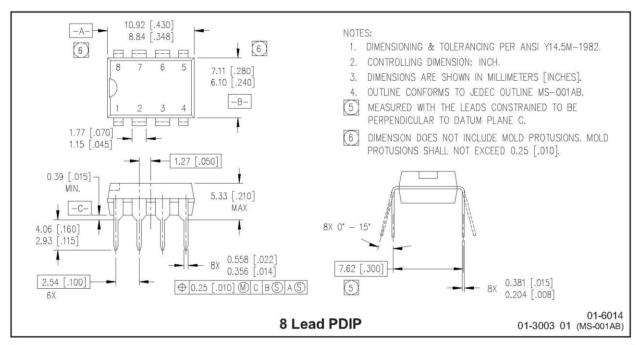
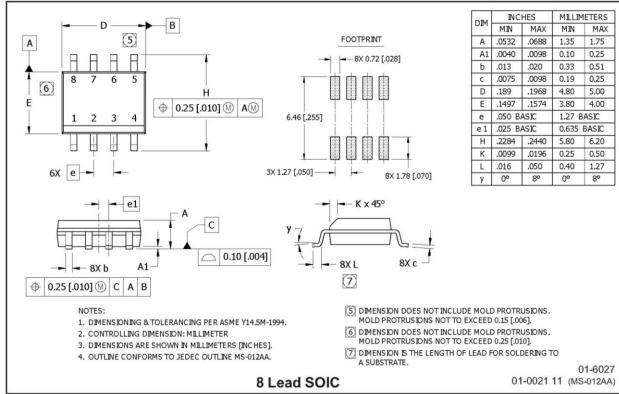


Figure 21. Maximum V<sub>S</sub> Negative Offset vs. V<sub>BS</sub> Floating Supply Voltage



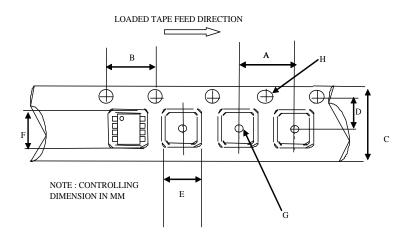
#### **Package Details**





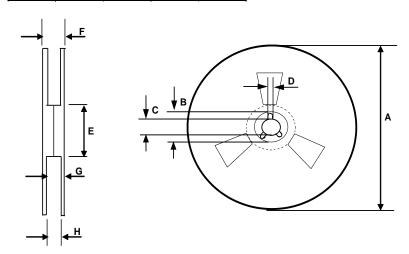


### **Tape and Reel Details**



CARRIER TAPE DIMENSION FOR 8SOICN

0,				
	Me	tric	Imp	erial
Code	Min	Max	Min	Max
Α	7.90	8.10	0.311	0.318
В	3.90	4.10	0.153	0.161
С	11.70	12.30	0.46	0.484
D	5.45	5.55	0.214	0.218
E	6.30	6.50	0.248	0.255
F	5.10	5.30	0.200	0.208
G	1.50	n/a	0.059	n/a
Н	1.50	1.60	0.059	0.062

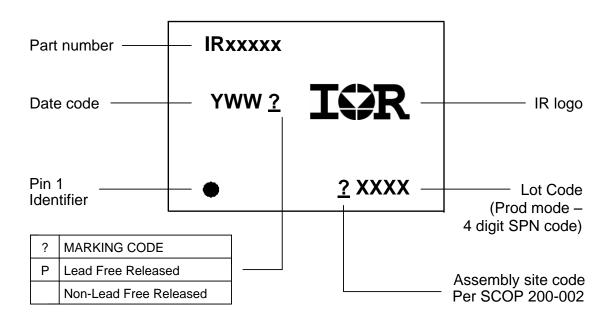


REEL DIMENSIONS FOR 8SOICN

	Me	etric	Imp	erial
Code	Min	Max	Min	Max
Α	329.60	330.25	12.976	13.001
В	20.95	21.45	0.824	0.844
С	12.80	13.20	0.503	0.519
D	1.95	2.45	0.767	0.096
E	98.00	102.00	3.858	4.015
F	n/a	18.40	n/a	0.724
G	14.50	17.10	0.570	0.673
Н	12.40	14.40	0.488	0.566



### **Part Marking Information**





#### Qualification Information<sup>†</sup>

Qualification informatio	••	
Qualification Level		Industrial <sup>††</sup> (per JEDEC JESD 47)
		Comments: This family of ICs has passed JEDEC's Industrial qualification. IR's Consumer qualification level is
		granted by extension of the higher Industrial level.
Moisture Sensitivity Level	8-Lead SOIC	MSL2 <sup>†††</sup> (per IPC/JEDEC J-STD-020)
RoHS Compliant		Yes

- † Qualification standards can be found at International Rectifier's web site <a href="http://www.irf.com/">http://www.irf.com/</a>
- †† Higher qualification ratings may be available should the user have such requirements. Please contact your International Rectifier sales representative for further information.
- ††† Higher MSL ratings may be available for the specific package types listed here. Please contact your International Rectifier sales representative for further information.

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